MICROCHIP Semiconductor Device Type: D5A 005 TSOT NiPdAu			Termination Base Alloy: Copper Alloy (Cu)			Package Homogeneous Materials: 8.1 Electronics (e.g. pc boards, displays)				J-STD-609A Product Marking and/or Pkg. Labeling e4
		"Contained In"	% Total				() , ()			
Basic Substance	CAS Number	Sub-Component	Weight	mg/part	ppm	8.02	(mg) Total	Mold Compound	% ot Total Weight	63.64
Silica, vitreous	60676-86-0	Mold Compound	54.094	6.816	540,940		Silica, vitreous	60676-86-0	85.00	
Epoxy Resin	Trade Secret	Mold Compound	3.898	0.491	38,980		Epoxy Resin	Trade Secret	6.13	
Phenolic Resin	Trade Secret	Mold Compound	3.898	0.491	38,980		Phenolic Resin	Trade Secret	6.13	
Epoxy, Cresol Novolac	29690-82-2	Mold Compound	1.559	0.196	15,592		Epoxy, Cresol Novolac	29690-82-2	2.45	
Carbon Black	1333-86-4	Mold Compound	0.191	0.024	1,909		Carbon Black	1333-86-4	0.30	
Copper	7440-50-8	Lead Frame	27.240	3.432	272,399			Total	100.00	
Iron	7439-89-6	Lead Frame	0.041	0.005	410	3.44	(mg) Total	Lead Frame	% of Total Weight	27.30
Phosphorous	7723-14-0	Lead Frame	0.011	0.001	109		Copper	7440-50-8	99.78	
Zinc (Metal)	7440-66-6	Lead Frame	0.008	0.001	82		Iron	7439-89-6	0.15	
Silver (Ag)	7440-22-4	Die Attach	1.554	0.196	15,543		Phosphorous	7723-14-0	0.04	
Proprietary Resin	Trade Secret	Die Attach	0.366	0.046	3,663		Zinc (Metal)	7440-66-6	0.03	
Proprietary Curing agent & Hardener	Trade Secret	Die Attach	0.059	0.007	594			Total	100.00	
Silicon	7440-21-3	Chip (Die)	3,760	0.474	37.600	0.25	(mg) Total	Die Attach	% of Total Weight	1.98
Gold	7440-57-5	Wire Bond	0.410	0.052	4,100		Silver (Ag)	7440-22-4	78.50	
Nickel	7440-02-0	Plating on external leads (pins)	2,619	0.330	26.190		Proprietary Resin	Trade Secret	18.50	
Palladium	7440-05-3	Plating on external leads (pins)	0.146	0.018	1,455	Pro	oprietary Curing agent & Hard	Trade Secret	3.00	
Gold	7440-57-5	Plating on external leads (pins)	0.146	0.018	1,455		photal y building agoin a mart	Total	100.00	
0014	11					0.47	Total (mg)			3 76
semiconductor device and its homogenous ma	aterials comply wit	TOTALS: g Total Mass h EU Directives: 2002/95/EC (27 January 2003) &	100.000	12.600	1,000,000	0.47	Total (mg) Doped Silicon	Chip (Die) 7440-21-3 Total	% of Total Weight 100.00 100.00	3.76
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